



Data Sheet

Customer:	
Part No:	CL-SFC281DBW-6.5K-90CRI
Sample No:	
Description:	2835 White SMD
Item No:	

Customer						
Check Inspection Approval Date						



Features:

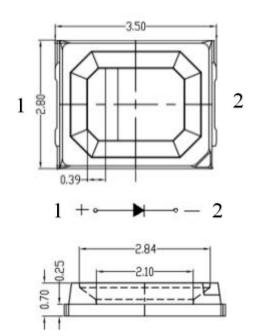
- . Reflow Solderable
- . High Luminous Intensity and Low Power Dissipation
- . Good Reliability and Long Life
- . Complied With RoHS Directive

Technical Data Sheet

This product is generally used as indicator and luminary for electronic equipment such as household appliance, communication equipment, and dashboard.

Applications

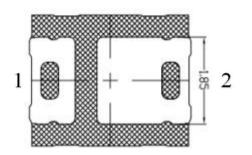
- Optical indicator
- Indoor display
- Backlighting in dashboard and switch
- Flat backlighting for LCD, symbol and display
- General use

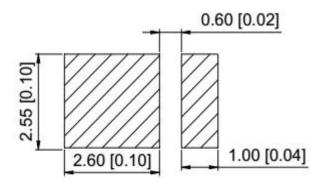


Notes:

- 1 . All dimension units are millimeters.
- 2. All dimension tolerance is ±0.2mm unless otherwise noted.









Selection Guide

Part No. Chij Materi	Chip	Lens Type	Luminous Flux(Lm) 60mA			Viewing Angle
	Materials		Min	Тур	Max	201/2
CL-SFC281DBW-6.5K-90CRI	InGaN	Yellow Diffused	22	24.5	26	120

Note:

 $1.2\theta 1/2$ is the angle from optical centerline where the luminous intensity is $2\theta 1/2$ the optical centerline value.

2. The above luminous intensity measurement allowance tolerance $\pm 10\%$

Electrical / Optical Characteristics at Ta=25°C

Parameter	Symbol	Min.	Тур.	Max	Units	test conditions
Forward Voltage	VF	2.8		3.4	V	IF=60mA
Reverse Current	IR			10	uA	VR = 5V
Color Rendering Index	CRI	90			/	IF=60mA
Color Temperature	Тс	6000		6500	К	IF=60mA

Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Rating	Units
Power Dissipation	Pd	200	mW
DC Forward Current	IF	IF 60	
Peak Forward Current [1]	IFP	120	mA
Reverse Voltage	VR	5	V
Electrostatic Discharge (HBM)	ESD	2000	V
Operating Temperature	Topr	-40~+85	°C
Storage Temperature	Tstg	-40~+100	°C

Note:

- 1. 1/10 Dut cycle,0.1ms pulse width.
- 2. The above forward voltage measurement allowance tolerance $\pm 0.1 V$.



Bin Range of FLUX

BIN	Code	min	max	Unit	IF
IM	K1	22	24	lm	COMA
LM	К2	24	26		60MA

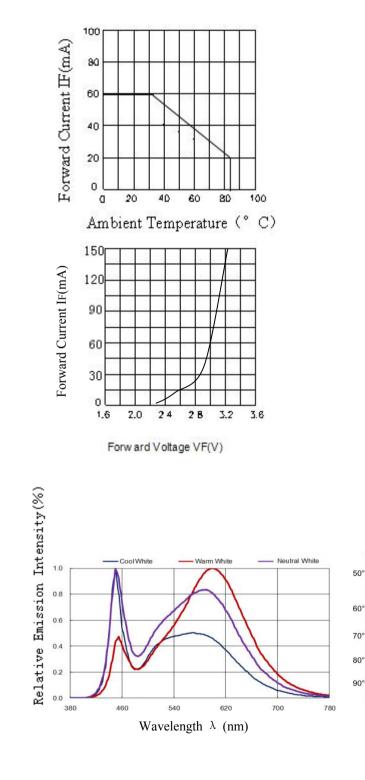
Bin Range of Forward Voltage

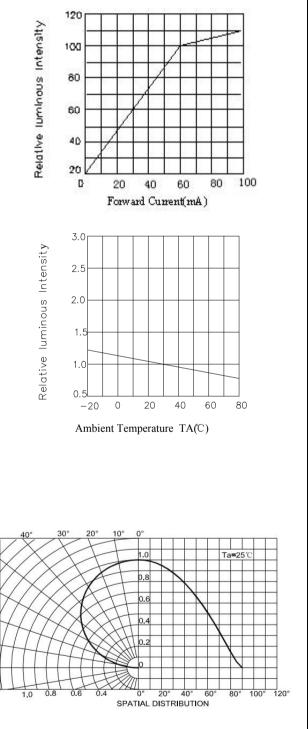
BIN	Code	min	max	Unit	IF
	V1	2.8	2.9	V	
	V2	2.9	3.0	V	
VF	V3	3.1	3.2	V	60MA
	V4	3.2	3.3	V	
	V5	3.3	3.4	V	



Typical optical characteristics curves

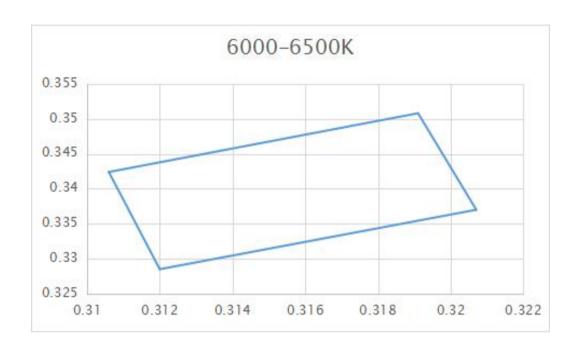
Ambient Temperature VS. Forward Current







Bin Color: IF=60MA



BIN	x	у
	0.3191	0.3508
2	0.3106	0.3424
6000-6500K	0.312	0.3285
-	0.3207	0.337
	0.3191	0.3508



Reliability Test Items And Conditions

Test Items	Ref.Standard	Test conditions	Time	Quantit y	Ac/Re
Reflow	JESD22-B106	Temp:260℃max T=10 sec	3 times.	22Pcs.	0/1
Temperature Cycle	JESD22-A104	-40°→30min 5 Cycles†↓shift(5)min 100°C →30 min. 25°C~55°C	100 Cycles	22Pcs.	0/1
High Temperature Storage	JESD22-A103	Temp:100 ℃ ±5 ℃	1000Hrs	22Pcs.	0/1
Low Temperature Storage	JESD22-A119	Temp:-40℃±5℃	1000Hrs	22Pcs.	0/1
Life Test	JESD22-A108	Ta=25℃±5℃ IF=60mA	1000Hrs	22Pcs.	0/1
High Temperature High Humidity Life Test	JESD22-A101	85℃±5℃/ 85%RH_IF=60mA	1000Hrs	22Pcs.	0/1

Criteria For Judging Damage

Test Items	Symbol	Test conditions	Criteria For Judgement	
			Min.	Max.
Forward Voltage	VF	IF=60mA		U.S.L*)x1.1
Reverse Current	IR	VR = 5V		U.S.L*)x2.0
Luminous intensity	mcd	IF=60mA	L.S.L*)x0.7	

U.S.L: Upper standard level L.S.L: Lower standard level

The technical information shown in the data sheets are limited to the typical characteristics and circuit examples

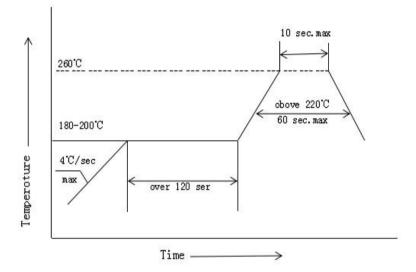
of the referenced products. It does not constitute the warranting of industrial property nor the granting of any license.



SMT Reflow Soldering Instructions SMT

1.Reflow soldering should not exceed once

2.When soldering , do not put stress on the LEDs during heating .

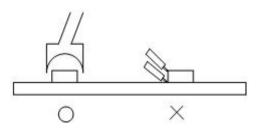


Soldering iron

- 1.When hand soldering, the temperature of the iron must less than 300 $^\circ\!{\rm C}$ for 3 seconds
- 2. The hand solder should be done only one times

Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of LEDs will or will not be damaged by repairing.





Storage

The package is sealed:

- 1.Recommended storage condition :At $5^{\circ}C$ ~30°C and relative humidity 90% RH max.
- 2.It is recommended that SMD out of their original packaging are used within one year.

The package is opened:

- 1.Completed within 168 hours.
- 2.Stored at5 $^\circ\!\mathrm{C}\text{--}30\,^\circ\!\mathrm{C}$ and 60% RH or less.
- 3.LEDs stored more than 168 hours should be baked at about 65 $^\circ\!C\pm\!5\,^\circ\!C$
- for at least 12 hours before solder assembly.

ESD

Static Electrisity will damage the LED.

The following procedures may decrease the possibility of ESD damage.

1.All productive machinery and test instruments must be electrically grounded.

2.Use a condustive wrist band or anti-electostatic glove when handling these LEDs.

3. Manintain a humidity level of 50% RHor higher in production areas.

4.Use anti-static packaging for transport and storage.

Handling Precautions

 1.Do not stack together assembled PCBs
 2.Not available in the situation of
 3.Electrostatic sensitive device

 containing LEDs. Impact may scratch the
 acidity for PH.

 silicone lens or damage.









